

ROUGHENED COPPER FOIL, COPPER-CLADDED LAMINATE BOARD, AND PRINTED
WIRING BOARD

ABSTRACT

5 Provided is a roughened copper foil capable of achieving both excellent transmission characteristics and high peel strength when used for a copper-clad laminate or a printed wiring board. This roughened copper foil includes a roughened surface on at least one side. The roughened surface has a roughness slope $\tan \theta$ of 0.58 or less as calculated based on a mean height R_c (μm) and a mean width R_{Sm} (μm) of profile elements by
10 formula $R_c/(0.5 \times R_{Sm})$, and a small projected area $R_c \times R_{Sm}$ of $0.45 \mu\text{m}^2$ or more and $2.00 \mu\text{m}^2$ or less that is a product of the mean height R_c (μm) and the mean width R_{Sm} (μm) of the profile elements. R_c and R_{Sm} are values measured in accordance with JIS B0601-2013 under a condition of not performing a cutoff by a cutoff value λ_s and a cutoff value λ_c .

Figure 1